

SOT683-1

plastic thermal enhanced ball grid array package; 960 balls;
body 33 x 33 x 2.4 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA960
Package type industry code	HBGA960
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	1-5-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		32.8	-	33	33.2	mm
E	package width		32.8	-	33	33.2	mm
A	seated height		[tbd]	-	3.1	3.1	mm
A ₂	package height		2.1	-	2.4	2.5	mm
n ₂	actual quantity of termination		-	-	960	-	



2. Package outline

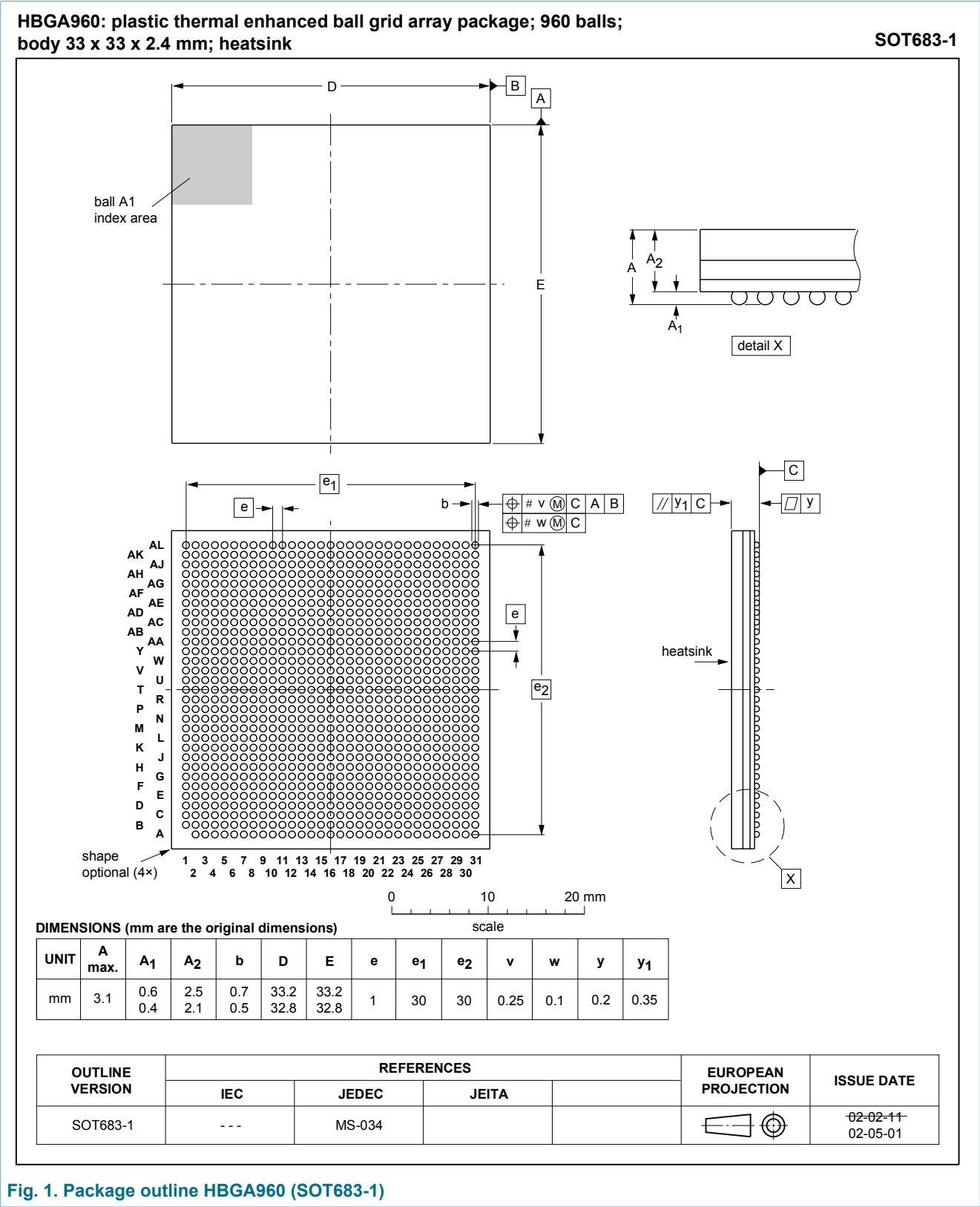


Fig. 1. Package outline HBGA960 (SOT683-1)

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3. Soldering

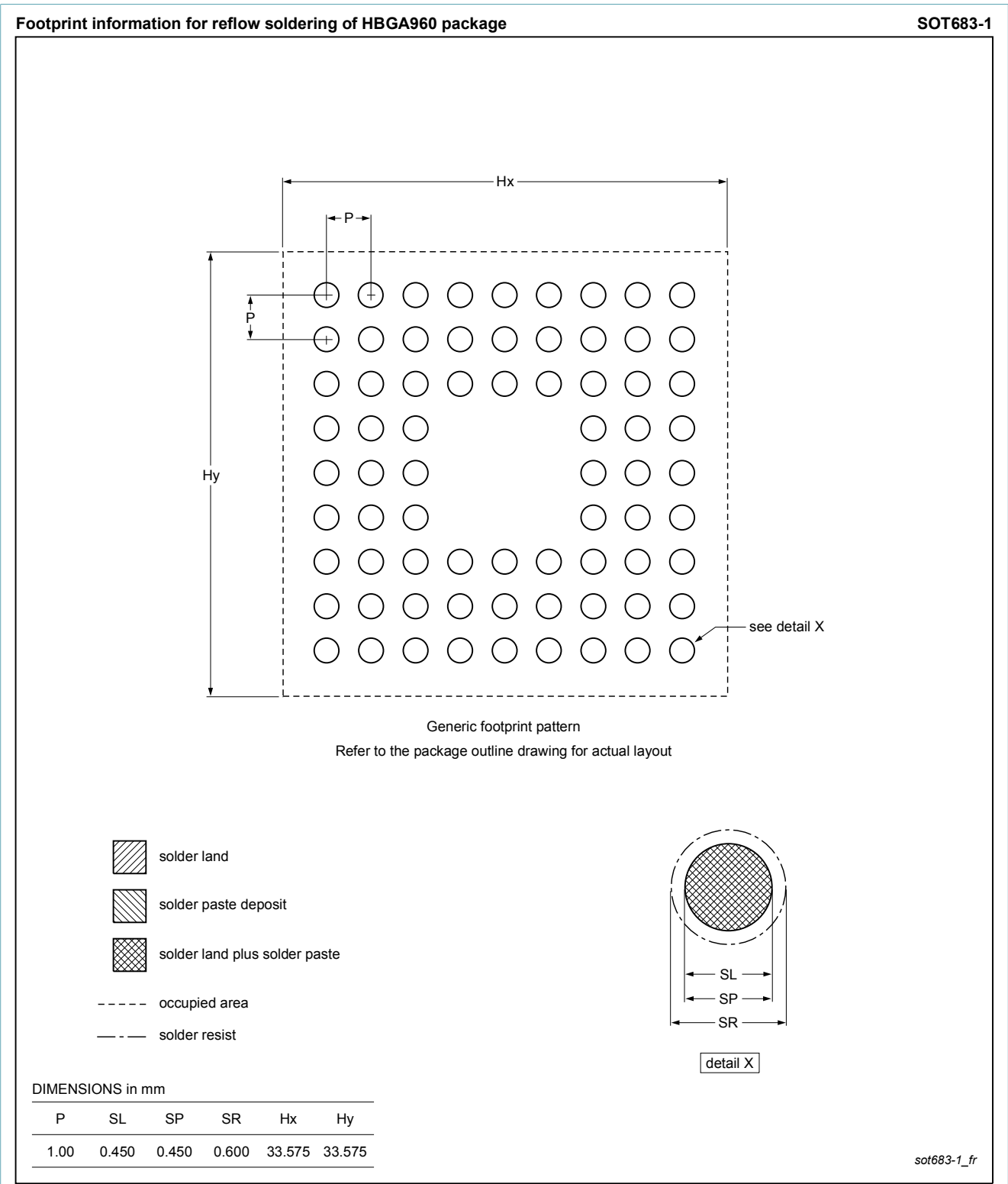


Fig. 2. Reflow soldering footprint for HBGA960 (SOT683-1)

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4. Legal information

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5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 4

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